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(12) **United States Design Patent**
Miller

(10) **Patent No.: US D838,325 S**
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(54) **WAFER PUCK**

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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **21-02**

(52) **U.S. Cl.**
USPC **D21/710**

(58) **Field of Classification Search**
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CPC A63B 43/002; A63B 65/10; A63B 67/06; A63B 67/14; A63B 69/0024; A63B 69/0026; A63B 69/3688; A63B 2102/22; A63B 2102/24; A63B 2244/15; A63F 7/40; A63F 2007/4068; A63F 7/06; A63F 7/0632; A63F 7/0668; A63F 9/0278; A63F 2009/0282; A63F 2009/0286; A63H 33/18; A63H 33/02
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

1,089,379	A	*	3/1914	McCracken	A44C 21/00 40/27.5
2,226,516	A	*	12/1940	Ross	A63B 67/14 473/588
3,766,452	A	*	10/1973	Burpee	G06K 19/067 194/214
3,773,325	A	*	11/1973	Crossman	A63F 7/3603 273/126 A
3,944,738	A	*	3/1976	Johnson	A63B 67/14 348/157
D367,902	S	*	3/1996	Silk	D21/710
D374,897	S	*	10/1996	Whisman	D21/710
D401,649	S	*	11/1998	Bellehumeur	D21/710
5,839,977	A	*	11/1998	Maurer	A63B 59/70 473/446
D405,606	S	*	2/1999	Merritt	D3/254
6,273,835	B1	*	8/2001	Battis	A63B 59/70 473/563
D512,064	S	*	11/2005	Li	D14/403
D561,852	S	*	2/2008	Frey	D21/710
D579,993	S	*	11/2008	Fairchild	D21/710

(Continued)

FOREIGN PATENT DOCUMENTS

CA	2306541	A1	*	10/2000	A63B 67/14
CA	2458489	A1	*	8/2004	A63B 67/14

(Continued)

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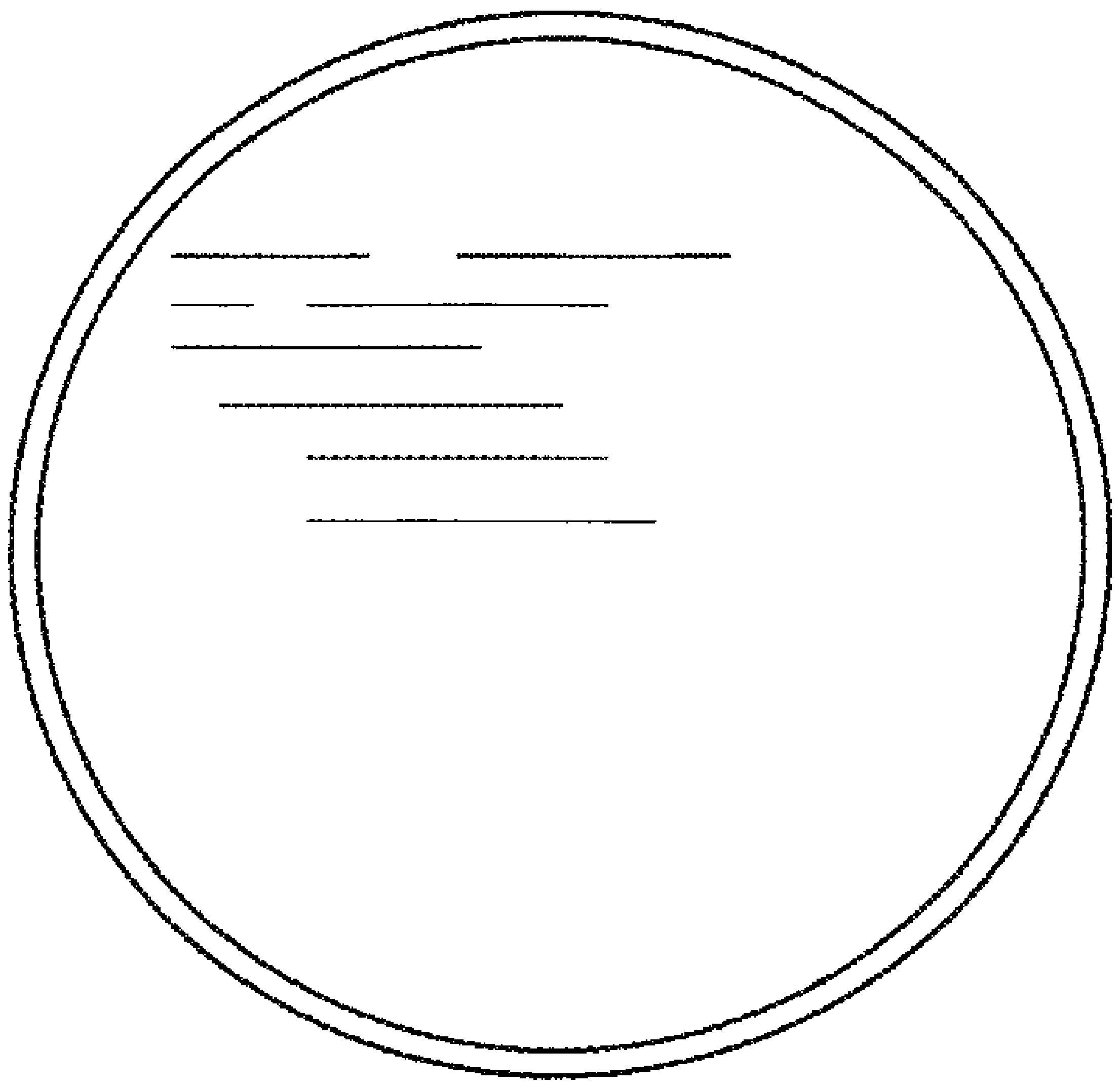
(57) **CLAIM**

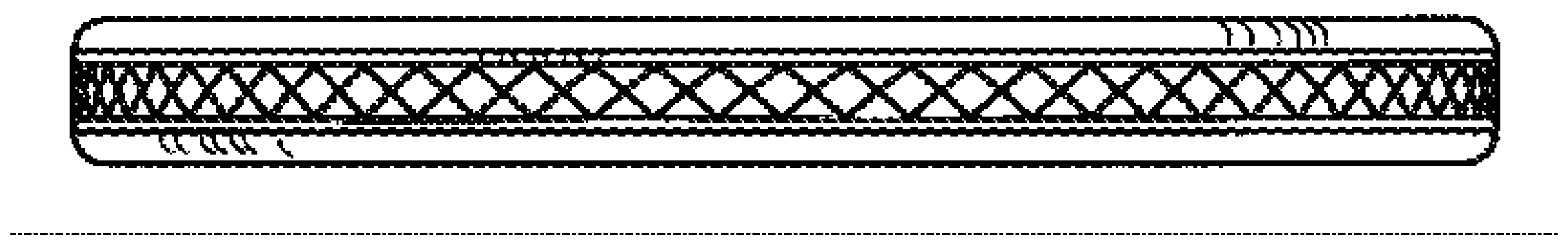
The ornamental design for a wafer puck, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of the first embodiment of my new design for a wafer puck;
FIG. **2** is a top perspective view thereof;
FIG. **3** is a side elevational view thereof;
FIG. **4** is a top plan view of the second embodiment of my new design for a wafer puck;
FIG. **5** is a top perspective view thereof; and,
FIG. **6** is a side elevational view thereof.

1 Claim, 2 Drawing Sheets





(56) **References Cited**

U.S. PATENT DOCUMENTS

D591,297	S *	4/2009	Manalo	D14/402
2003/0084695	A1 *	5/2003	Stark	A63B 67/14 72/70
2005/0130775	A1 *	6/2005	Hylak	A63B 67/04 473/588
2006/0267273	A1 *	11/2006	Chen	A63F 7/06 273/126 R
2009/0029812	A1 *	1/2009	Tsai	A63B 67/14 473/588

FOREIGN PATENT DOCUMENTS

CH	532941	A *	1/1973	A63F 7/06
RU	2031678	C1 *	3/1995	

* cited by examiner

Figure 1.

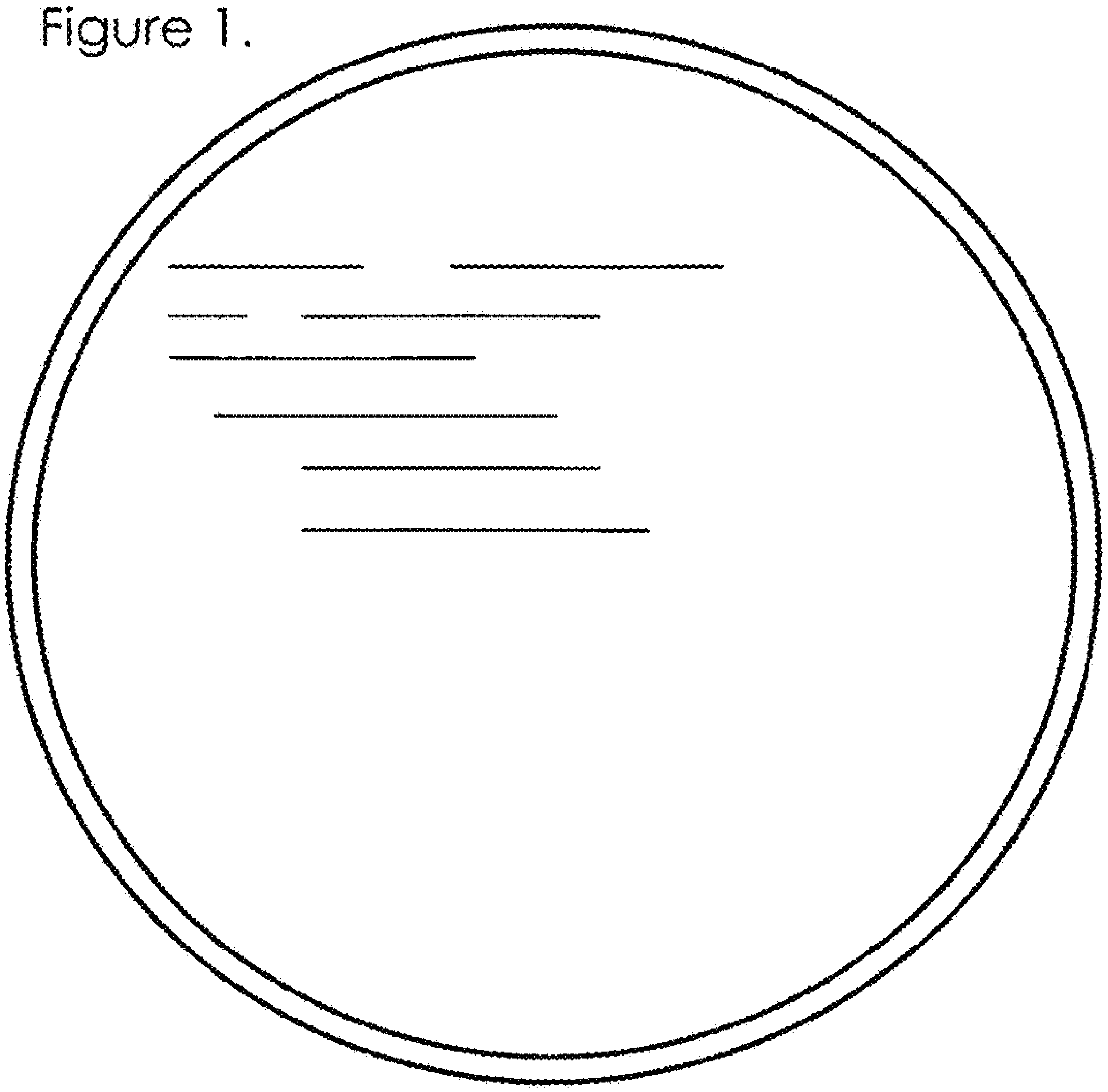
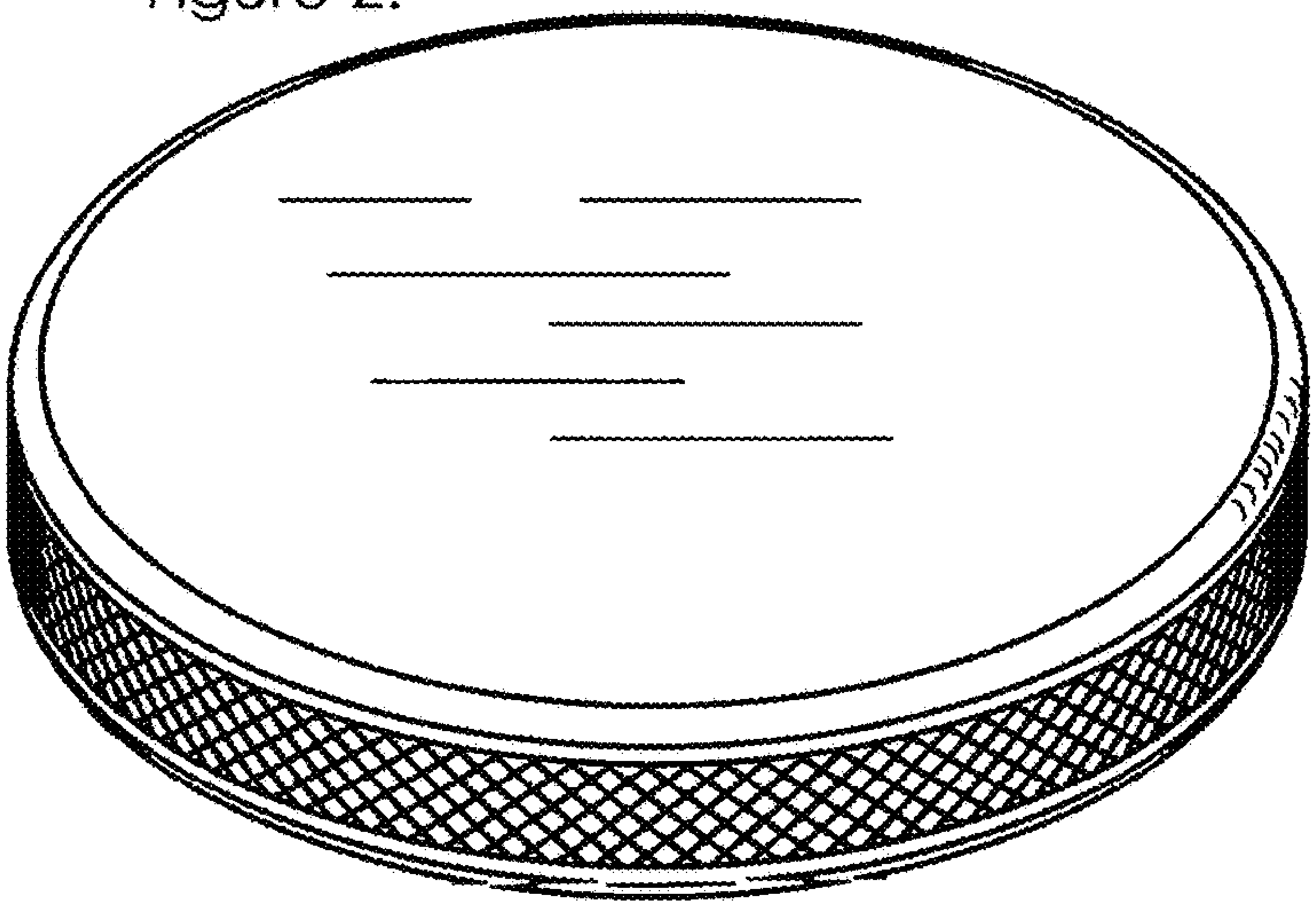


Figure 2.



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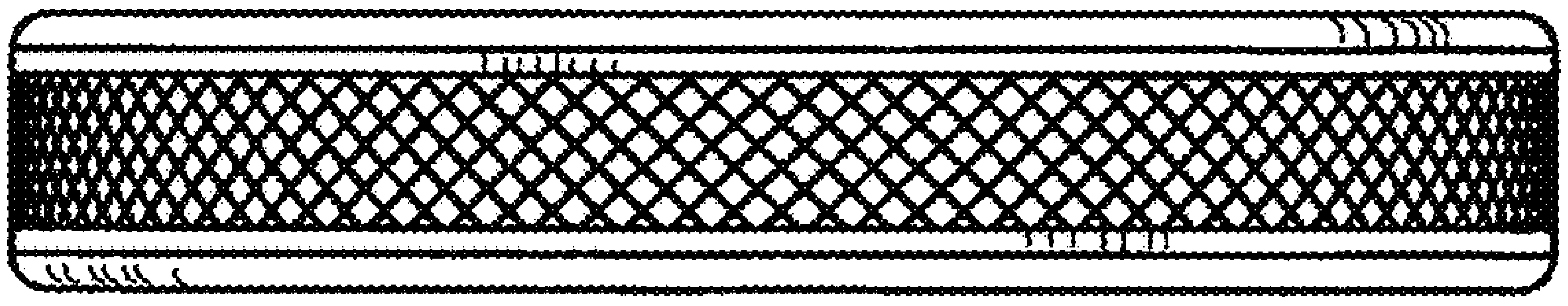

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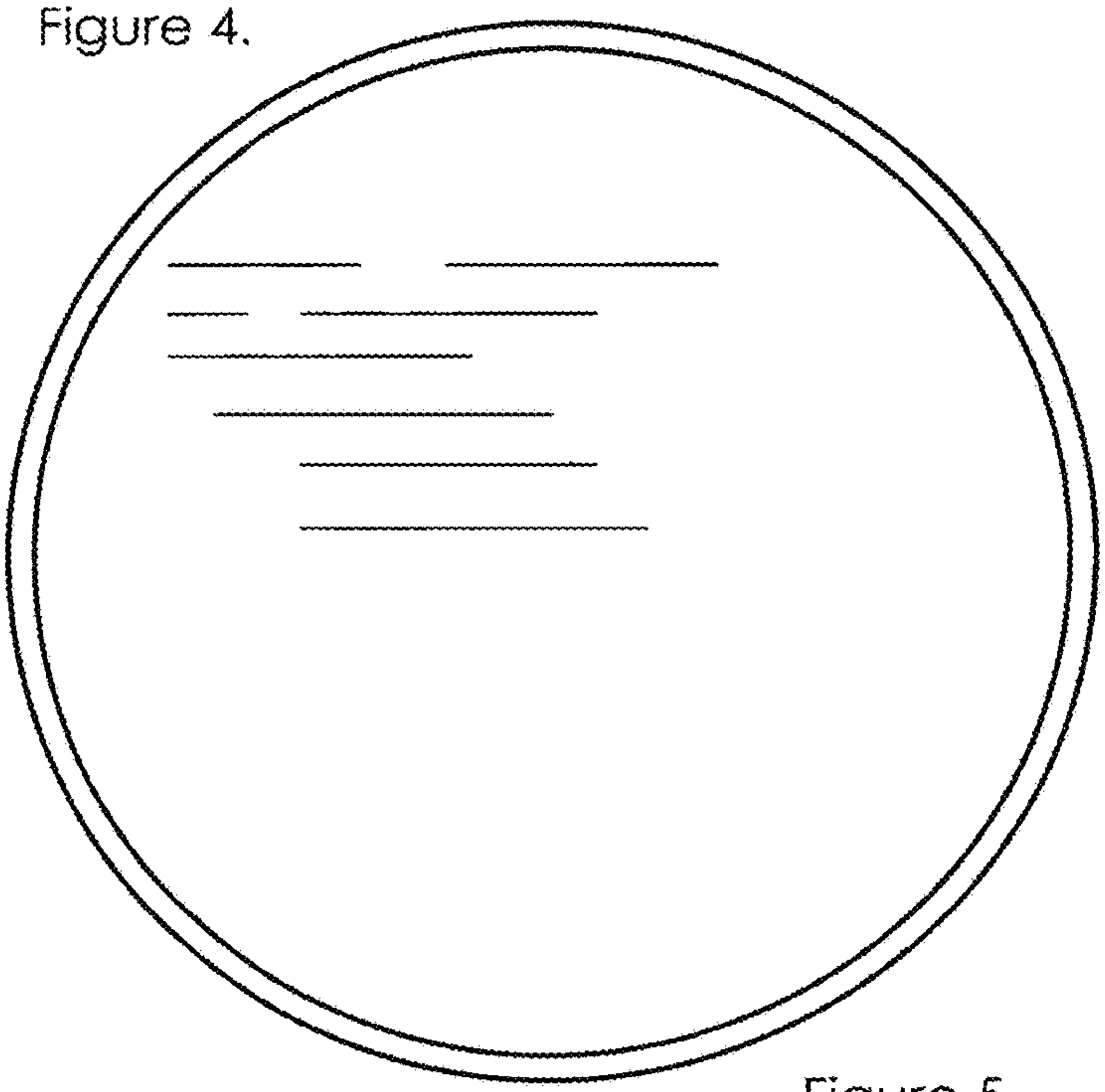

Figure 5.

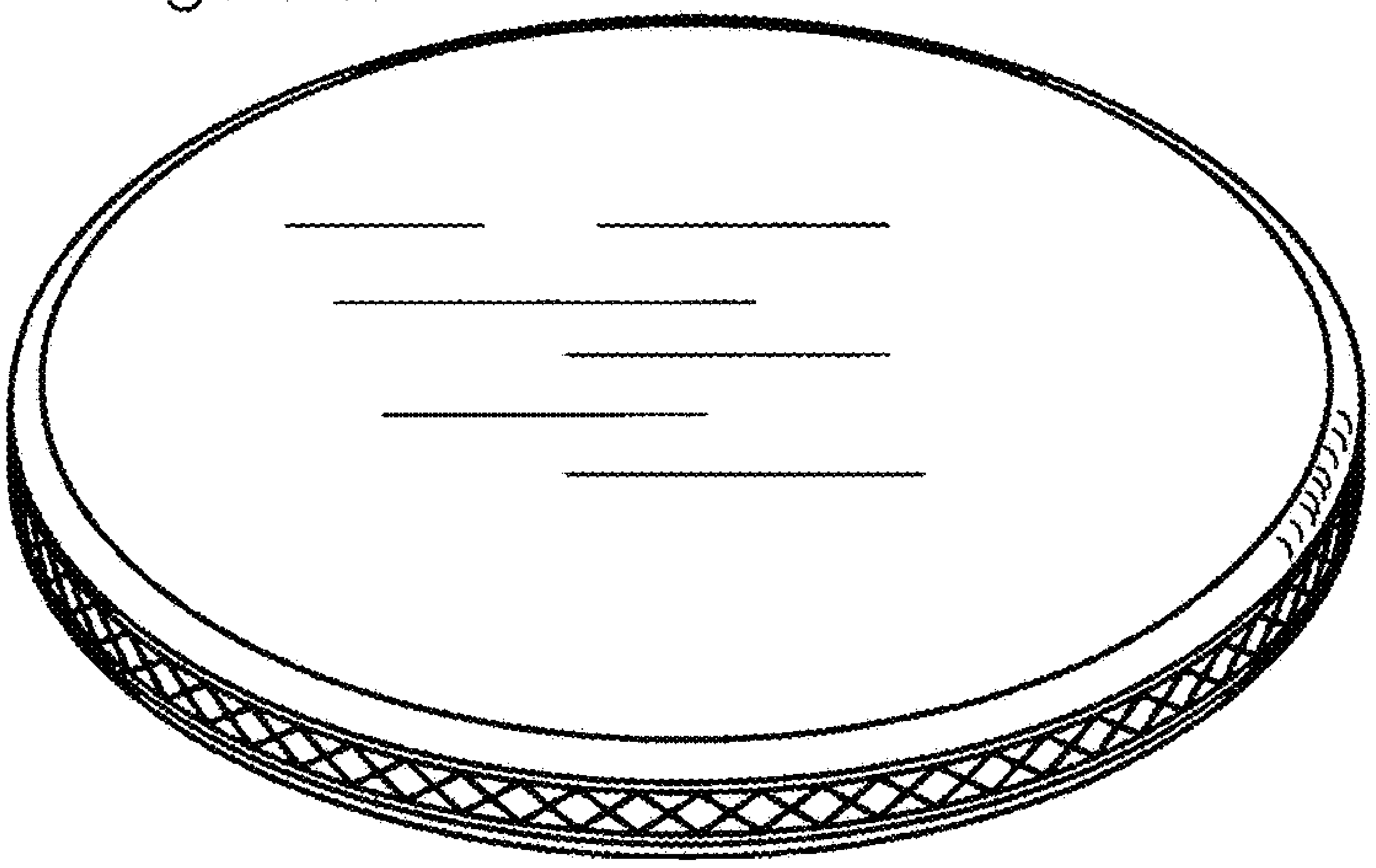

Figure 6.